



High Speed Infrared Emitting Diodes, 940 nm, GaAIAs, MQW



DESCRIPTION

VSMB2943SLX01 is an infrared, 940 nm, side looking emitting diode in GaAIAs multi quantum well (MQW) technology with high radiant power and high speed, molded in clear, untinted plastic package (with lens) for surface mounting (SMD).

APPLICATIONS

- IrDA compatible data transmission
- Miniature light barrier
- Photointerrupters
- Optical switch
- Remote control
- IR touch panels

FEATURES

- Package type: surface mount
- Package form: side view
- Dimensions (L x W x H in mm): 2.3 x 2.55 x 2.3
- AEC-Q101 qualified
- Peak wavelength: $\lambda_p = 940 \text{ nm}$
- High reliability
- High radiant power
- High radiant intensity
- Angle of half intensity: $\phi = \pm 25^\circ$
- Low forward voltage
- Suitable for high pulse current operation
- Package matches with detector VEMD2023SLX01 and VEMT2023SLX01
- Floor life: 4 weeks, MSL 2a, acc. J-STD-020
- Material categorization: For definitions of compliance please see www.vishay.com/doc?99912



PRODUCT SUMMARY				
COMPONENT	I_e (mW/sr)	ϕ (deg)	λ_p (nm)	t_r (ns)
VSMB2943SLX01	20	± 25	940	15

Note

- Test conditions see table "Basic Characteristics"

ORDERING INFORMATION			
ORDERING CODE	PACKAGING	REMARKS	PACKAGE FORM
VSMB2943SLX01	Tape and reel	MOQ: 3000 pcs, 3000 pcs/reel	Side view

Note

- MOQ: minimum order quantity

ABSOLUTE MAXIMUM RATINGS ($T_{amb} = 25^\circ\text{C}$, unless otherwise specified)				
PARAMETER	TEST CONDITION	SYMBOL	VALUE	UNIT
Reverse voltage		V_R	5	V
Forward current		I_F	100	mA
Peak forward current	$t_p/T = 0.5, t_p = 100 \mu\text{s}$	I_{FM}	200	mA
Surge forward current	$t_p = 100 \mu\text{s}$	I_{FSM}	1	A
Power dissipation		P_V	160	mW
Junction temperature		T_j	100	$^\circ\text{C}$
Operating temperature range		T_{amb}	-40 to +85	$^\circ\text{C}$
Storage temperature range		T_{stg}	-40 to +100	$^\circ\text{C}$
Soldering temperature	according figure 9, J-STD-020	T_{sd}	260	$^\circ\text{C}$
Thermal resistance junction/ambient	J-STD-051, leads 7 mm, soldered on PCB	R_{thJA}	250	K/W

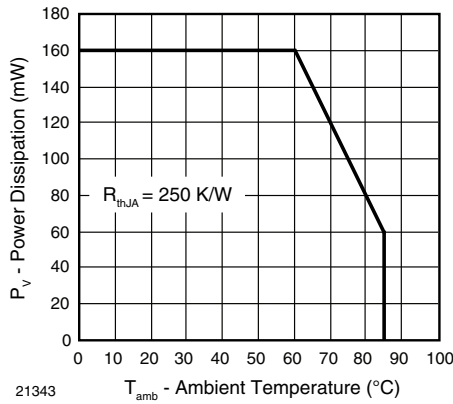


Fig. 1 - Power Dissipation Limit vs. Ambient Temperature

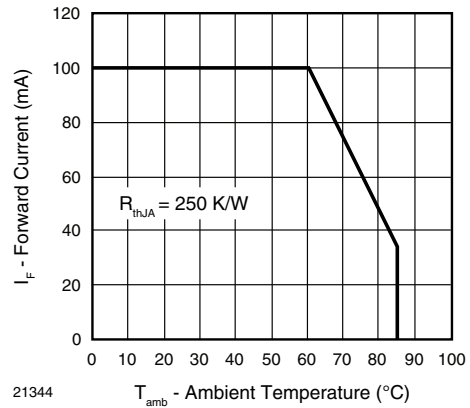


Fig. 2 - Forward Current Limit vs. Ambient Temperature

BASIC CHARACTERISTICS (T _{amb} = 25 °C, unless otherwise specified)						
PARAMETER	TEST CONDITION	SYMBOL	MIN.	TYP.	MAX.	UNIT
Forward voltage	I _F = 100 mA, t _p = 20 ms	V _F	1.15	1.35	1.6	V
	I _F = 1 A, t _p = 100 μs	V _F		2.2		V
Temperature coefficient of V _F	I _F = 1 mA	TK _{V_F}		-1.8		mV/K
	I _F = 100 mA	TK _{V_F}		-1.1		mV/K
Reverse current		I _R	Not designed for reverse operation			μA
Junction capacitance	V _R = 0 V, f = 1 MHz, E = 0 mW/cm ²	C _J		70		pF
Radiant intensity	I _F = 100 mA, t _p = 20 ms	I _e	10	20	30	mW/sr
	I _F = 1 A, t _p = 100 μs	I _e		170		mW/sr
Radiant power	I _F = 100 mA, t _p = 20 ms	φ _e		40		mW
Temperature coefficient of radiant power	I _F = 1 mA	TK _{φ_e}		-1.1		%/K
	I _F = 100 mA	TK _{φ_e}		-0.51		%/K
Angle of half intensity		φ		± 25		deg
Peak wavelength	I _F = 30 mA	λ _p	920	940	960	nm
Spectral bandwidth	I _F = 30 mA	Δλ		25		nm
Temperature coefficient of λ _p	I _F = 30 mA	TKλ _p		0.25		nm/K
Rise time	I _F = 100 mA, 20 % to 80 %	t _r		15		ns
Fall time	I _F = 100 mA, 20 % to 80 %	t _f		15		ns
Cut-off frequency	I _{DC} = 70 mA, I _{AC} = 30 mA pp	f _c		23		MHz

BASIC CHARACTERISTICS ($T_{amb} = 25\text{ }^{\circ}\text{C}$, unless otherwise specified)

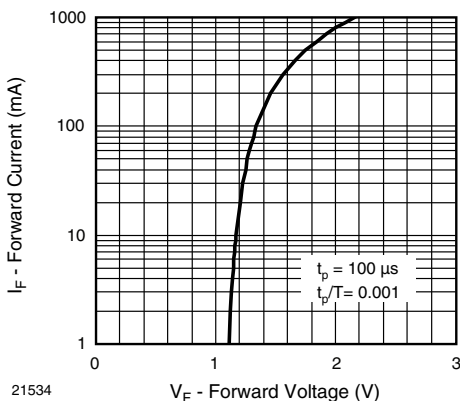


Fig. 3 - Forward Current vs. Forward Voltage

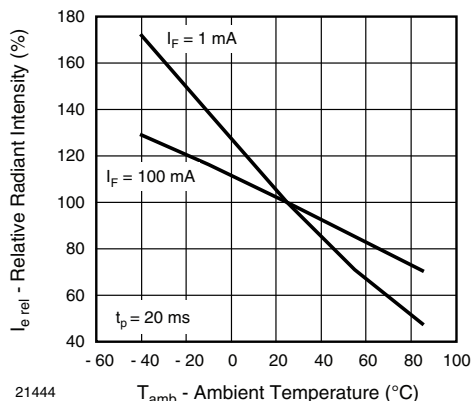


Fig. 6 - Relative Radiant Intensity vs. Ambient Temperature

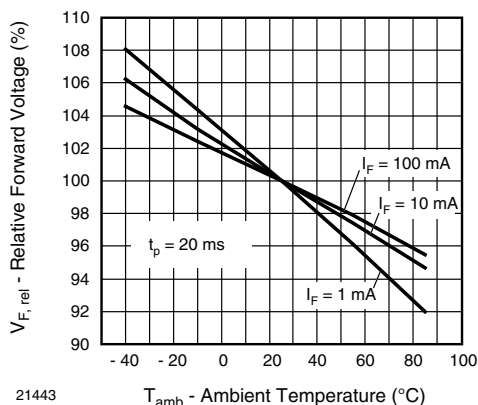


Fig. 4 - Relative Forward Voltage vs. Ambient Temperature

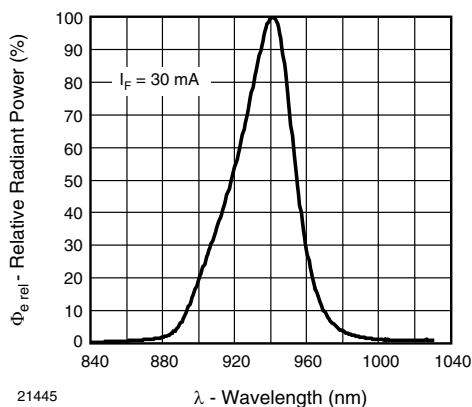


Fig. 7 - Relative Radiant Power vs. Wavelength

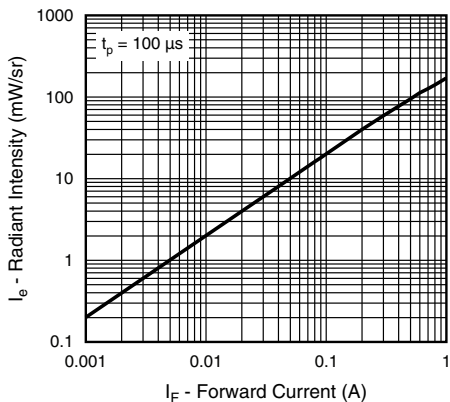


Fig. 5 - Radiant Intensity vs. Forward Current

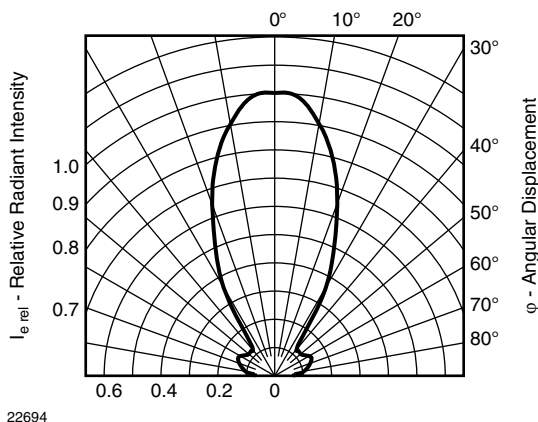


Fig. 8 - Relative Radiant Intensity vs. Angular Displacement

SOLDER PROFILE

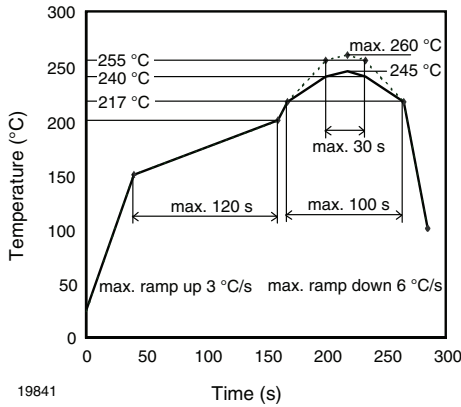


Fig. 9 - Lead (Pb)-free Reflow Solder Profile acc. J-STD-020

DRYPACK

Devices are packed in moisture barrier bags (MBB) to prevent the products from moisture absorption during transportation and storage. Each bag contains a desiccant.

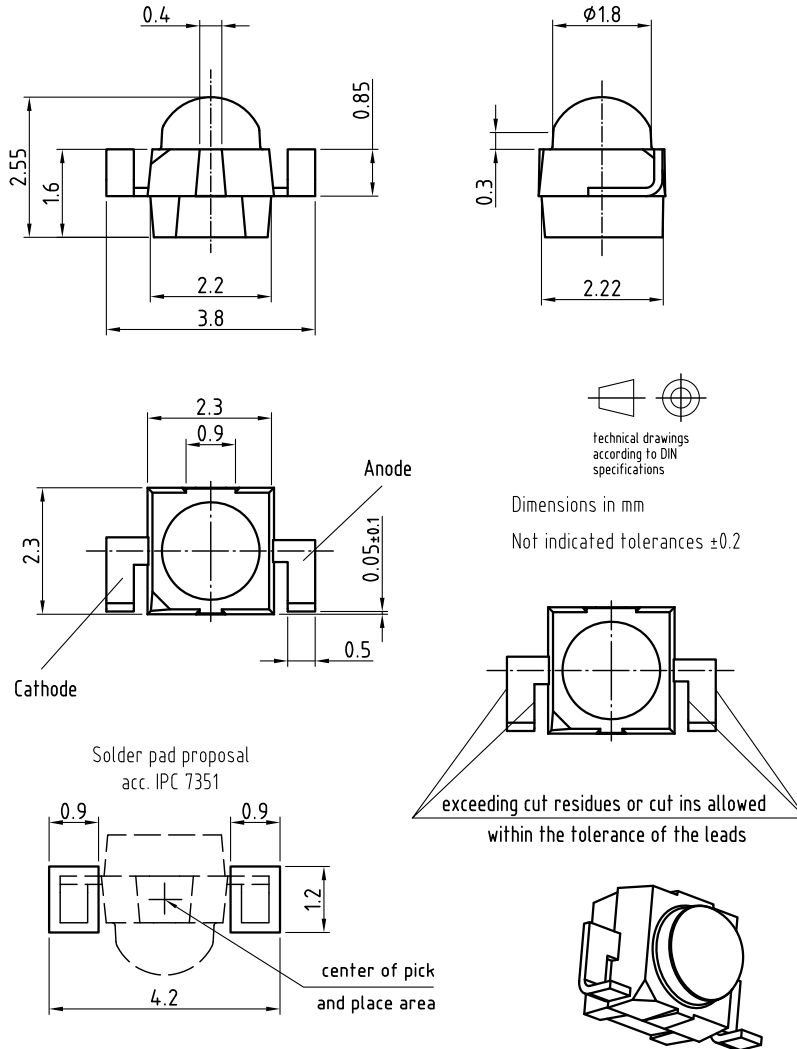
FLOOR LIFE

Floor life (time between soldering and removing from MBB) must not exceed the time indicated on MBB label:
Floor life: 4 weeks
Conditions: $T_{amb} < 30\text{ °C}$, $RH < 60\%$
Moisture sensitivity level 2a, acc. to J-STD-020.

DRYING

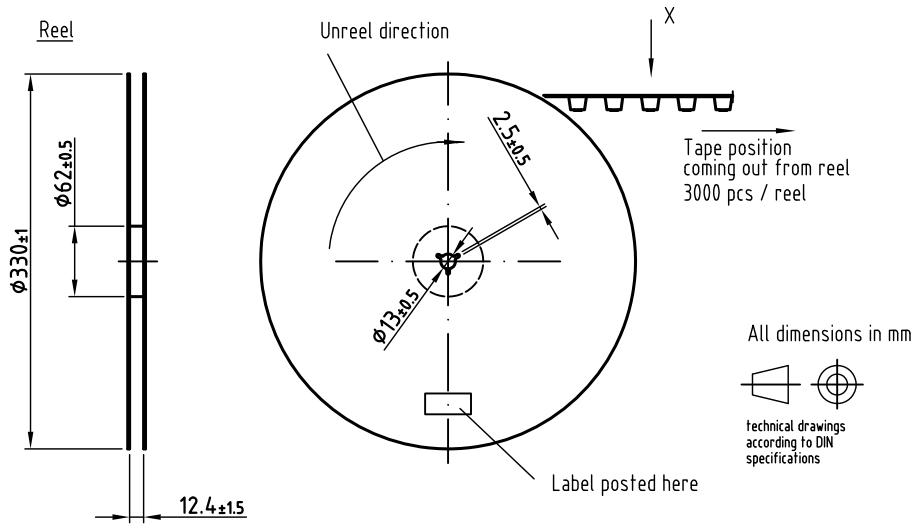
In case of moisture absorption devices should be baked before soldering. Conditions see J-STD-020 or label.
Devices taped on reel dry using recommended conditions 192 h at $40\text{ °C} (+5\text{ °C})$, $RH < 5\%$.

PACKAGE DIMENSIONS in millimeters: **VSMB2943SL**

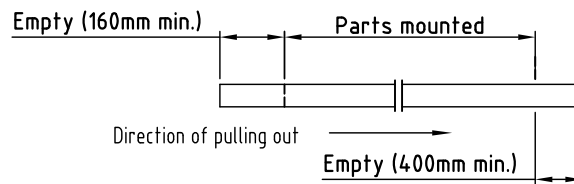


Drawing refers to following types: VSMB2943SLX01
VSMF2893SLX01
Drawing-No.: 6.544-5410.02-4 VSMB2948SL
Issue: prel. 03.08.12 VEMD2x23SLX01

TAPING AND REEL DIMENSIONS in millimeters: VSMB2943SL

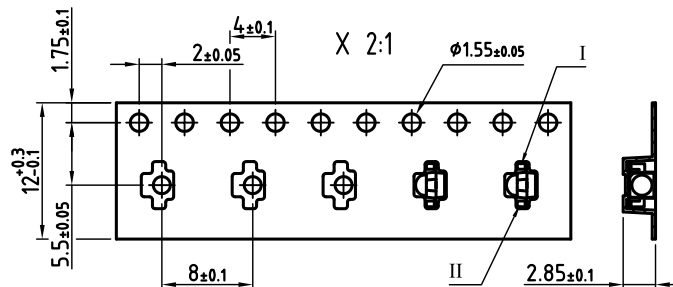


Leader and trailer tape:



Terminal position in tape

Device	Lead I	Lead II
VSMB2943SLX01	Cathode	Anode
VSMF2893SLX01		
VSMB2948SL		
VEMD2023SLX01		
VEMD2523SLX01	Collector	Emitter
VEMT2023SLX01		
VEMT2523SLX01	Anode	Cathode



Drawing refers to following types: see table
Reel dimensions and tape

Drawing-No.: 9.800-5123.01-4
Issue: prel; 01.02.13



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